



**PATENT**

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicants:	Hiroshi SAKAI, et al.	Examiner:	Kevin L. McHenry	
Serial No.:	10/063,915	Art Unit:	1725	
Filed:	May 23, 2002	Docket:	15574	
For:	SOLDER PASTE PRINTING METHOD AND APPARATUS FOR PRINTING SOLDER PASTE ON A BOARD ON WHICH WIRING PATTERNS ARE FORMED		Dated:	October 9, 2003

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

**INFORMATION DISCLOSURE STATEMENT**

Sir:

In accordance with 37 C.F.R. §§1.97 and 1.98, it is requested that the following references, which are also listed on the attached Form PTO-1449, be made of record in the above-identified case.

1. Japanese Laid-Open Patent Application No. 5-96842, dated April 20, 1993;
2. Japanese Laid-Open Patent Application No. 11-1325, dated January 6, 1999;

**CERTIFICATE OF MAILING UNDER 37 C.F.R. §1.8(a)**

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450 on October 9, 2003.

Dated: October 9, 2003

  
Paul J. Esatto, Jr.

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3. Japanese Laid-Open Patent Application No. 9-62146, dated March 7, 1997;
4. Japanese Laid-Open Patent Application No. 11-347789, dated December 21, 1999; and
5. Japanese Laid-Open Patent Application No. 11-300492, dated November 2, 1999.

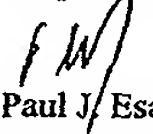
The references listed above were cited in an Official Action dated August 26, 2003 received from the Japanese Patent Office. Applicants are submitting copies of the above references, together with an English translation of the Examiner's comments regarding the references from the Official Action. Please note that the other references cited in the Official Action, namely, Japanese Laid-Open Patent Application No. H10-217425, dated August 18, 1998 and Japanese Laid-Open Patent Application No. 2001-47601, dated February 20, 2001, were previously submitted in applicants' Information Disclosure Statement dated August 7, 2003. The relevance of the references is described in the Official Action.

In compliance with the requirements of 37 C.F.R. §1.98(a)(3), as a concise statement of relevance, as it is presently understood by the individual designated in 37 C.F.R. §1.56(c) most knowledgeable about the content of the information, the undersigned attorney of record submits a translation of portions of an official action by a foreign examiner in which the references were cited. The relevance to the pending U.S. patent application is that the references were cited in a foreign patent application on the same subject matter. However, no independent analysis of the references, the accuracy of the statement of the foreign examiner or the claims of the foreign application under the laws of that country or the United States relative to the subject matter claimed in the present application has been made; the present understanding of the

contents thereof by the undersigned being based on the translation of the foreign examiner's comments submitted herewith.

Inasmuch as this Information Disclosure Statement is being submitted in accordance with the schedule set out in 37 C.F.R. § 1.97(c), the statement is enclosed.

Respectfully submitted,

  
Paul J. Esatto, Jr.  
Registration No. 30,749

Scully, Scott, Murphy & Presser  
400 Garden City Plaza  
Garden City, New York 11530  
(516) 742-4343

PJE:AVS:jap



**PATENT**

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

**Applicants:** Hiroshi SAKAI, et al.

**Examiner:** Kevin L. McHenry

**Serial No.:** 10/063,915

**Group:** 1725

**Filed:** May 23, 2002

**Docket:** 15574

**For:** SOLDER PASTE PRINTING METHOD  
AND APPARATUS FOR PRINTING  
SOLDER PASTE ON A BOARD ON  
WHICH WIRING PATTERNS ARE FORMED

**Dated:** October 9, 2003

Commissioner for Patents  
P. O. Box 1450  
Alexandria, VA 22313-1450

**STATEMENT PURSUANT  
TO 37 C.F.R. § 1.97(c)(1) and (e)(1)**

Sir:

I hereby state that each item of information contained in this Information Disclosure Statement was first cited in any communication from a foreign patent office in a counterpart foreign application not more than three months prior to the filing of this Information Disclosure Statement.

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**CERTIFICATE OF MAILING UNDER 37 C.F.R. §1.8(a)**

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450 on October 9, 2003.

Dated: October 9, 2003

  
Paul J. Esatto, Jr.

Accordingly, it is respectfully requested that the accompanying Information Disclosure Statement be considered with respect to the above-identified application.

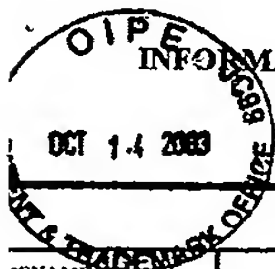
Respectfully submitted,



Paul J. Esatto, Jr.  
Registration No. 30,749

Scully, Scott, Murphy & Presser  
400 Garden City Plaza  
Garden City, New York 11530  
(516) 742-4343

PJE:AVS:jap

**INFORMATION DISCLOSURE CITATION**

(Use several sheets if necessary)

Docket Number (Optional)

15574

Application Number

10/063,915

Applicant(s)

Hiroshi SAKAI, et al.

Filing Date

May 23, 2002

Group Art Unit

1725

**U.S. PATENT DOCUMENTS**

EXAMINER INITIAL	REF	DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE

**FOREIGN PATENT DOCUMENTS**

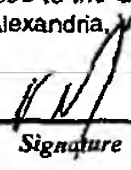
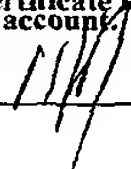
	REF	DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	Translation	
							YES	NO
		5-96842	4/20/1993	Japan				
		11-1325	1/6/1999	Japan				
		9-62146	3/7/1997	Japan				
		11-347789	12/21/1999	Japan				
		11-300492	11/2/1999	Japan				

**OTHER DOCUMENTS** (Including Author, Title, Date, Pertinent Pages, Etc.)


EXAMINER

DATE CONSIDERED

EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP Section 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

<b>TRANSMITTAL OF INFORMATION DISCLOSURE STATEMENT</b> (Under 37 CFR 1.97(b) or 1.97(e))			Docket No. 15574
In Re Application: <b>Hiroshi SAKAI, et al.</b>			
Serial No. 10/063,915	Filing Date May 23, 2002	Examiner Kevin L. McHenry	Group Art Unit 1725
<b>SOLDER PASTE PRINTING METHOD AND APPARATUS FOR PRINTING SOLDER PASTE ON A BOARD ON WHICH WIRING PATTERNS ARE FORMED</b>			
<b>Payment of Fee</b> (Only complete if Applicant elects to pay the fee set forth in 37 CFR 1.17(p))			
<input type="checkbox"/> A check in the amount of _____ is attached. <input checked="" type="checkbox"/> The Director is hereby authorized to charge and credit Deposit Account No. <b>19-1013/SSMP</b> as described below.			
<input type="checkbox"/> Charge the amount of _____ <input checked="" type="checkbox"/> Credit any overpayment. <input checked="" type="checkbox"/> Charge any additional fee required.			
<b>Certificate of Transmission by Facsimile*</b>		<b>Certificate of Mailing by First Class Mail</b>	
I certify that this document and authorization to charge deposit account is being facsimile transmitted to the United States Patent and Trademark Office (F):  _____ (Date)  _____ Signature  _____ Typed or Printed Name of Person Signing Certificate		I certify that this document and fee is being deposited on <b>October 9, 2003</b> with the U.S. Postal Service as first class mail under 37 C.F.R. 1.8 and is addressed to the Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.   Signature Paul J. Esatto, Jr.  _____ Typed or Printed Name	
*This certificate may only be used if paying by deposit account.  Signature			
Dated: <b>October 9, 2003</b>			
<b>Paul J. Esatto, Jr.</b> <b>Registration No. 30,749</b> <b>SCULLY, SCOTT, MURPHY &amp; PRESSER</b> <b>400 Garden City Plaza</b> <b>Garden City, NY 11530</b> <b>(516) 742-4343</b> <b>PJE:AVS:jap</b>  cc:			

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 Sale Ref: 00000001 DA# 191013 10063915  
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<b>TRANSMITTAL OF INFORMATION DISCLOSURE STATEMENT</b> (Under 37 CFR 1.97(b) or 1.97(c))			<b>Docket No.</b> 15574
In Re Application Of: Hiroshi SAKAI, et al.			
<b>Serial No.</b> 10/063,915	<b>Filing Date</b> May 23, 2002	<b>Examiner</b> Kevin L. McHenry	<b>Group Art Unit</b> 1725
<b>Title: SOLDER PASTE PRINTING METHOD AND APPARATUS FOR PRINTING SOLDER PASTE ON A BOARD ON WHICH WIRING PATTERNS ARE FORMED</b>			
<p>Address to: Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450</p> <p><b>37 CFR 1.97(b)</b></p> <p>1. <input type="checkbox"/> The Information Disclosure Statement submitted herewith is being filed within three months of the filing of a national application other than a continued prosecution application under 37 CFR 1.53(d); within three months of the date of entry of the national stage as set forth in 37 CFR 1.491 in an international application; before the mailing of a first Office Action on the merits, or before the mailing of a first Office Action after the filing of a request for continued examination under 37 CFR 1.114.</p> <p><b>37 CFR 1.97(c)</b></p> <p>2. <input checked="" type="checkbox"/> The Information Disclosure Statement submitted herewith is being filed after the period specified in 37 CFR 1.97(b), provided that the Information Disclosure Statement is filed before the mailing date of a Final Action under 37 CFR 1.113, a Notice of Allowance under 37 CFR 1.311, or an Action that otherwise closes prosecution in the application, and is accompanied by one of:</p> <p><input checked="" type="checkbox"/> the statement specified in 37 CFR 1.97(e);</p> <p><b>OR</b></p> <p><input type="checkbox"/> the fee set forth in 37 CFR 1.17(p).</p>			